



MMIC DIE

Gain Equalizer

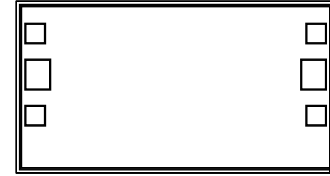
EQY-18-24-D+

Mini-Circuits

50Ω 6 to 18 GHz

THE BIG DEAL

- 18 dB Slope
- Insertion Loss, 20.4 dB Typ. at 6 GHz
- Insertion Loss, 2.2 dB Typ. at 18 GHz
- Return Loss, 20 dB Typ.



+RoHS Compliant
 The +Suffix identifies RoHS Compliance.
 See our website for methodologies and qualifications

SEE ORDERING INFORMATION ON THE LAST PAGE

APPLICATIONS

- Test and Measurement
- EW, Radar, and ECM Defense Systems
- Back Haul Radio

PRODUCT OVERVIEW

Mini-Circuits' EQY-18-24-D+ is a MMIC Gain Equalizer fabricated using highly repeatable GaAs IPD MMIC process incorporating resistors, capacitors, and inductors to accomplish a positive Insertion Loss Slope vs. Frequency. EQY-18-24-D+ has a nominal Insertion Loss Slope of 18 dB across the wide bandwidth of 6 to 18 GHz and can be applied to compensate for the negative Gain Slope of amplifiers to achieve relative Gain Flatness for the overall system.

KEY FEATURES

Features	Advantages
Positive Insertion Loss Slope vs. Frequency	Useful for compensating negative Gain Slope of amplifiers, filter effects in receivers, and transmitters to achieve Flat Gain versus Frequency.
Wideband Operation, 6 to 18 GHz	Supports a wide array of applications including Test & Measurement, EW, Radar, and ECM Defense Systems, and Back Haul radio.
Excellent Power Handling Capability	Enables its use at the output of a variety of amplifiers.
Unpackaged Die	Enable user to integrate it directly into hybrids.

REV. OR
 ECO-014697
 EQY-18-24-D+
 MCL NY
 220823





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ELECTRICAL SPECIFICATIONS¹ AT 25°C, 50Ω, UNLESS OTHERWISE NOTED.

Parameter	Condition (GHz)	Min.	Typ.	Max.	Units
Frequency Range		6		18	GHz
Insertion Loss	6	-	20.4	-	dB
	10	-	13.5	-	
	14	-	6.7	-	
	16	-	4.1	-	
	18	-	2.2	-	
VSWR	6-10	-	1.11	-	:1
	10-14	-	1.13	-	
	14-16	-	1.17	-	
	16-18	-	1.35	-	

1. Die is soldered in a 16L 3x3mm package and measured on Mini-Circuits Characterization Test Board TB-EQY-18-24C+. See Characterization & Application Circuit (Fig.1).

MAXIMUM RATINGS²

Parameter	Ratings
Operating Case Temperature	-55°C to +105°C
Storage Temperature	-65°C to +150°C
RF Input Power ³	+33 dBm (5 minute max) +30 dBm (continuous)

2. Permanent damage may occur if any of these limits are exceeded.

3. Derates linearly to +29 dBm at +105°C



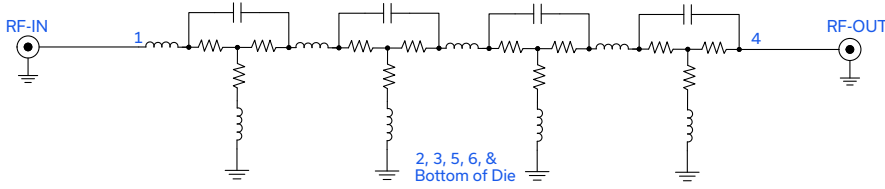
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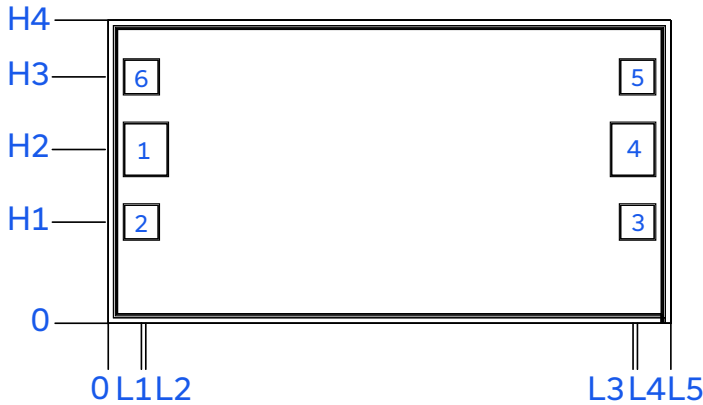
SIMPLIFIED SCHEMATIC



PAD DESCRIPTION

Function	Pad Number	Description
RF-IN	1	RF-Input Pad
RF-OUT	4	RF-Output Pad
GND	2, 3, 5, 6, & Bottom of the die.	The bond pads are connected to back-side through vias and do not require wire-bond connections to ground.

BONDING PAD POSITION



DIE DIMENSIONS IN μm, TYP.

L1	L2	L3	L4	L5
92	104	1446	1459	1550

H1	H2	H3	H4
279	479	679	835

Thickness	Die size	Pad Size 1 & 4	Pad Size 2,3,5 & 6
100	1550 x 835	117 x 142	92 x 92

CHARACTERIZATION & APPLICATION CIRCUIT

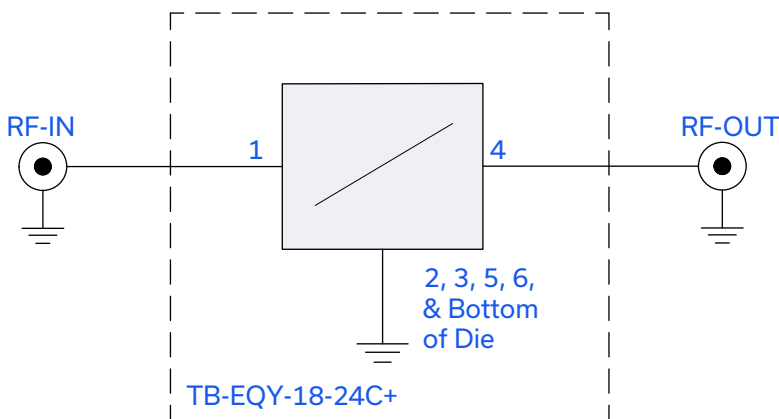


Fig 1. Characterization & Application Circuit

Note: This block diagram is used for characterization.

(DUT is soldered into a 16L 3x3mm package and measured on Mini-Circuits characterization test board TB-EQY-18-24C+. Insertion loss and Return Loss are measured using Keysight N5245A PNA-X Microwave Network Analyzer.

Condition:

Insertion Loss & Return Loss: Pin = 0 dBm



MMIC DIE

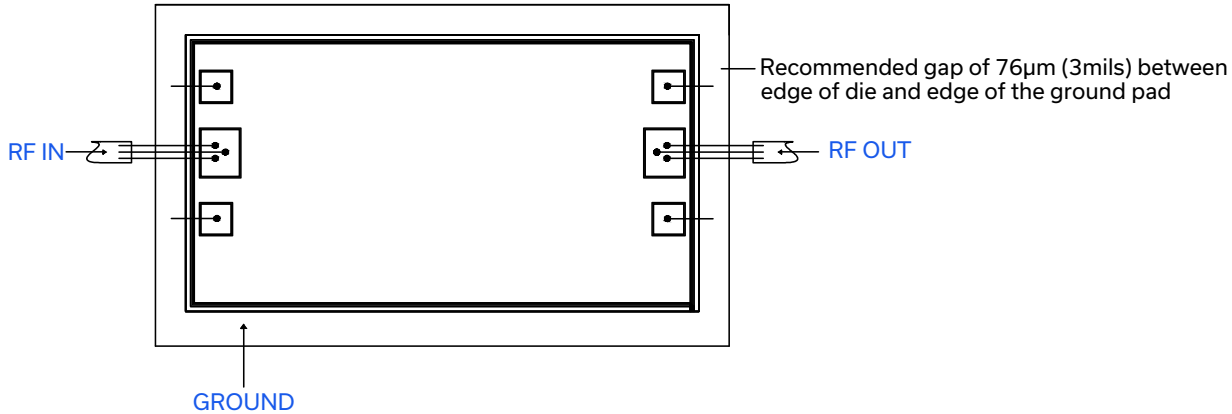
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ASSEMBLY DIAGRAM



ASSEMBLY PROCEDURE

- Storage**
Die should be stored in a dry nitrogen purged desiccators or equivalent.
-  **ESD**
MMIC Equalizer die are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be open in clean room conditions at an appropriately grounded anti-static workstation.
- Die Handling and Attachment**
Devices need careful handling using correctly designed collets, it is recommended to handle the chip along the edges with a custom design collet. The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are Ablestik 84-1 LMISR4 or equivalents. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. The surface of the chip has exposed air bridges and should not be touched with vacuum collet, tweezers or fingers.
- Wire Bonding**
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the die gold bond pads. Thermo-sonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1mil diameter. Bonds must be made from the bond pads on the die to the packaged or substrate. All bond wire length and bond wire height should be kept as short as possible unless specified by the Assembly Drawing to minimize performance degradation due to undesirable series inductance.

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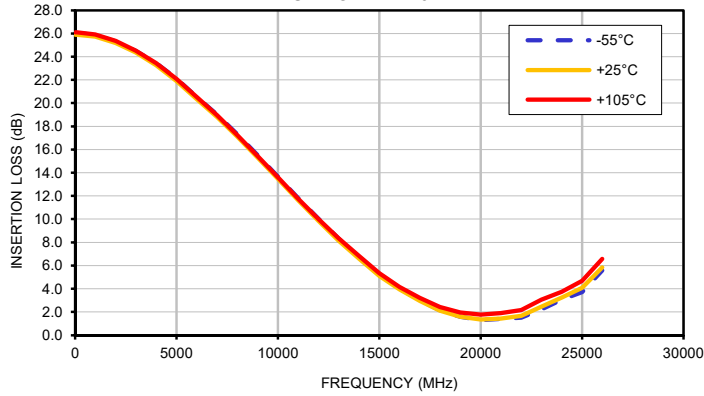
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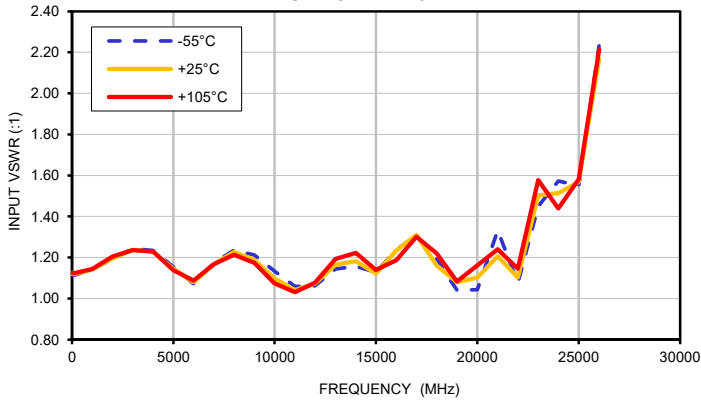
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TYPICAL PERFORMANCE CURVES

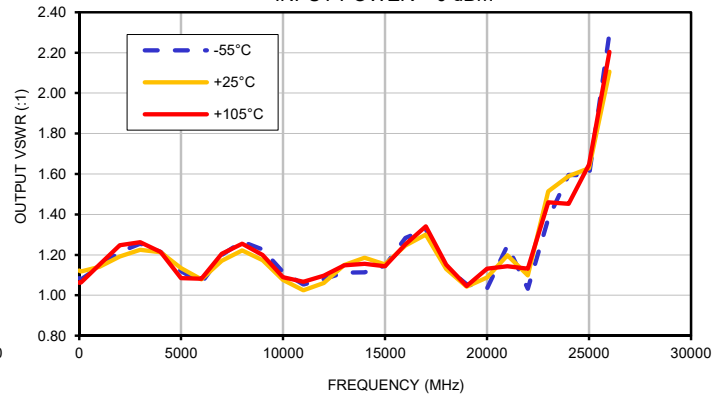
INSERTION LOSS vs. TEMPERATURE
INPUT POWER = 0 dBm



INPUT VSWR vs. TEMPERATURE
INPUT POWER = 0 dBm



OUTPUT VSWR vs. TEMPERATURE
INPUT POWER = 0 dBm





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ADDITIONAL DETAILED TECHNICAL INFORMATION IS AVAILABLE ON OUR DASH BOARD.

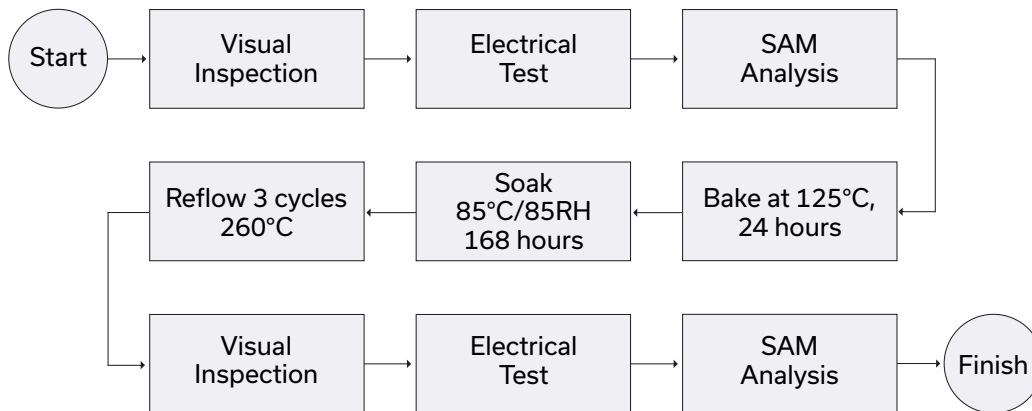
Performance Data	Data Table
	Swept Graphs
	S-Parameter (S2P Files) Data Set with and without port extension(.zip file)
Case Style	Die
Die Ordering and packaging information	Quantity, Package Small, Gel - Pak: 5,10,50,100 KGD* Medium†, Partial wafer: KGD*<1247 Full wafer †Available upon request contact sales representative Refer to AN-60-067
Die Marking	JU18E
Environmental Ratings	ENV80

Known Good Die ('KGD') means that the die in question have been subjected to Mini-Circuits DC test performance criteria and measurement instructions and that the parametric data of such die fall within a predefined range. While DC testing is not definitive, it does provide a higher degree of confidence that die are capable of meeting typical RF electrical performance specified by Mini-Circuits.

ESD RATING**

Human Body Model (HBM): Class 1C (1000V to < 2000V) in accordance with ANSI/ESD STM 5.1 - 2001 Machine Charged Device Model (CDM): Class 1B (500V to < 1000V) in accordance with ANSI/ESD 5.2-2001

MSL TEST FLOW CHART



NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
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